**“Gary” Dae Yong Yu**

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**Position applied:** Heateflex product sales and marketing manager

**Professional Summary**

* 12 years of semiconductor capital equipment sales experience with **>$250M** of purchase order record primarily from global semiconductor manufacturing company including Samsung by launching beta system sales targeted key customer R&D engineers for bridging pilot to mass production proliferation by successful customer process spec qualifications through mutual demo condition adjustment and result analysis over competition including Applied Material by CoO advantage and price negotiation yet securing corporate gross margin and practiced accurate quarterly and annual sales forecast reporting for US semiconductor equipment suppliers including Genus (Varian) - PECVD & High Energy Implant, GaSonics (LAM)- PR strip & light etching, Semitool(AMAT)- Copper electroplating, Verteq (Akrion) - Ultrasonic wet cleaning, for Korea key accounts including Global Samsung, SK Hynix, LG Electron, Amkor, Dongbu.
* 4 Years of semiconductor equipment OEM business with **$85M** sales record of wafer and FPD process chamber / robot systems for Korean local OEMs including ADP, SEMES, Jusung Engineering, for Samsung & LG Display and overseas end users including Chimei (CMO) Taiwan and BOE in China **(Brooks Automation)** and process gas components including regulators, valves, filters, fittings and IGS marketing for **TKSCT(Fujikin Korea)** to wafer process equipment OEMs including Eugenetech, ADP, Jusung Engineering, IPS with **$45M** sales record.
* 5 years of LDI (Laser Direct Imaging) system business for Korean PCB market by integrating engineering and marketing team of Aiscent head office in Zhongshan China.

Technical introduction of 405nm multi-light engine imaging system for <10um line/space circuit registration on thin photoresist for multi-layer PCB manufacturing to major PCB suppliers including Samsung Electro-Mechanics (SEMCO), Interflex, Korea Circuit for HDI (High Density Interconnect) PCBs and memory packaging providers.

* Compelling strategic key account sales planning for each beta project by maintaining intelligence network with key customers for soonest reporting of new process development status and capex plan to alert for headquarters and provided quarterly sales plan on Miller Heiman CRM formality.
* Periodical intelligence report on customer product technology roadmap, capex plan, decision channel analysis, competitor’s activity and propose counter strategy by Miller Heiman sales planning and Weight matrix analysis.
* Conducted strategic beta system demo condition negotiation including customer process implemented throughput requirement by estimating number of chambers etc., quote, volume / unit negotiation, manufacturing slot line up, delivery, installation, acceptance and warranty support plan to meet customer mass production roadmap.
* Install site red flag response with customer support, engineering for early recovery and CIP execution on engineering modification for throughput, uniformity, MTTR, MTBF improvement.
* Quarterly VOC(voice of customer) survey, escalation and improvement status report.
* Schedule customer technology update meeting and Semicon show preparation, layout and budgetary proposal.
* Have long term personal relationship with senior engineers of Samsung Austin, Global Foundry in Malta and Singapore, and AMAT, LAM in US and Korea.
* Strong technical presentation skill and computer literacy with English/Korean translation capability and flexibility to multinational culture with bilingual in English / Korean and basic Japanese.
* **Work Experiences**
* **Aiscent Technology : Sales Representative for Korea - 2013 ~ 2018**

**Responsibility:** Establish sales and marketing outpost in Korea for LDI (Laser Direct Imaging) system business for Korean PCB market by integrating engineering and marketing executives of Aiscent head office in Zhongshan China.

* Technical introduction to major PCB suppliers including Samsung Electro-Mechanics (SEMCO), Interflex, Korea Circuit for HDI (High Density Interconnect) and packaging providers.
* **Dongah Geological Engineering Co.,** : **ESVP of Environment Business Div. - 2010 ~ 2012**

**Responsibilities:** Managing Environment BU for market development of OEM business for global wastewater and desalination system engineering sales. - Commissioned three 35KT/day DAF (Dissolved Air-Floatation) systems for municipal wastewater treatment facility for T-P, T-N elimination at Miryang city Korea to protect Naktong river line from red-tide and green tide at southern coastlines.

* **TKSCT Corporation (Fujikin): Managing Director, Global Sales & Marketing - 2007 ~ 2009**

**Responsibilities:** Managing corporate sales team and representative sales network and achieved **$50M** sales revenue by selling UHP fittings, valves, regulators and filters to global market including Samsung, Hynix, Fuji Electric plat in Malaysia and GCE Germany.

* Started IGS product marketing for Korean local CVD, Etching suppliers.
* Accommodated factory audit by LAM for supplier qualification.
* **Brooks Automation USA.: Sr. Director of Sales for Korea - 2005 ~ 2007**

**Responsibilities**: Wafer / FPD handling robot, platform / process chamber, FOUP sales record of **$80M** from semiconductor and FPD OEMs including Jusung Engineering, ADP, IPS, Eugenetech and end user product sales for Samsung and Hynix.

- Conducted customer spec based technical conferences for atmospheric / vacuum robot and chamber for semiconductor and FPD fabrication for Samsung, LG, CMO Taiwan, AUO China.

* **Consulting, Korea sales for Semitool(Applied Mat’l) & Verteq Inc (Akrion).,- 2003 ~ 2004**

**Responsibilities:** Developing Semitool Raider multi-electrode electro copper plating market competing Novellus Saber and Verteq Gold Finger single wafer mega-sonic wet cleaning market targeting Samsung and Amkor.

* Signed out JDP projected Gold Finger system after a year of production trial at Samsung R & D line and collected years of due $**1.1M** of conditional payment.
* 24 system order of Gold Finger followed for mass production at Line- 8,9 after merged by Akrion.
* **Gasonics (LAM) USA** : **Korea Country Manager - 2000 ~ 2002**

**Responsibilities:** Managing Korean sales and service group

**-** Tripled sales revenue to **$20M** of photo-resist stripping and etching systems from Samsung by paradigm changing customer support by pull-in OEM supplier and provided free replacement of poorly performing 16 Kensington robots at Samsung line-8 with Yaskawa robots on supplier’s cost and made Yaskawa qualified for subsequent orders.

* Had Hynix accepted 1 Iridia light etch system after a year of JDP.
* **Aju-Exim/ Genus (Aixtron) : Customer support Director, Country manager - 1994 ~ 2000**

**Responsibilities:** Managing Korean strategic accounts including Samsung Kiheung and Austin TX and Hynix to secure sales record of $250M total and support install bases of WSix PECVD and High Energy Implant systems.

* Relocated to Genus HQ in Sunnyvale CA USA in 1996 for strategic Samsung account management by integrating engineering and product support resources for 24X7 coverage.

**Education & Professional Training**

* Electrical engineering principle and basic electronics from Seongdong technical high school in Seoul Korea.
* 16 weeks of Surveillance Radar repair and maintenance courses from Korean Army and served for 3 years and discharged as a technical sergeant.
* 24 months plus of technical and sales marketing training courses in US, Japan, UK and Hongkong.

**Genus Inc., (Eugenus & Varian) USA**

2 weeks of product and process training on Tungsten Silicide PECVD systems in Sunnyvale, CA (1994) & 2 weeks of High Energy Implant systems in Newburyport MA.USA

Miller Heiman strategic sales training.

**Therma-Wave Inc., (KLA) USA**

16 weeks plus of laser applied Therma probe Implant monitoring and Thin film thickness measurement systems from Therma-Wave Inc., Fremont, CA. USA.

**Eaton Semiconductor equipment Corp**. **(Axcelis)USA**

16 weeks of technical training for maintenance and operation on Photolithographic Stepper 8005HR system for 1.0um resolution by 5:1 reticle reduction exposure to silicon wafer.

24 weeks of High current Implant, Medium current implant systems from Eaton training center in Austin TX and Beverly MA.

**Sales track record and training certificates are available upon request.**

**US Citizen since 2005.**